

HM50N06P 60V N-Channel MOSFET Features: <ul style="list-style-type: none"> <input type="checkbox"/> Low Intrinsic Capacitances. <input type="checkbox"/> Excellent Switching Characteristics. <input type="checkbox"/> Extended Safe Operating Area. <input type="checkbox"/> Unrivalled Gate Charge :$Q_g = 31\text{nC}$ (Typ.). <input type="checkbox"/> $BVDSS=60\text{V}, I_D=50\text{A}$ <input type="checkbox"/> $R_{DS(on)} : 21\text{m}\Omega$ (Max) @ $V_G=10\text{V}$ <input type="checkbox"/> 100% Avalanche Tested 	<div style="text-align: center;"> TO-220 1.Gate (G) 2.Drain (D) 3.Source (S) </div>
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Absolute Maximum Ratings* (T_c=25°C unless otherwise noted)

Symbol	Parameter	Value	Unit
V_{DSS}	Drain-Source Voltage	60	V
I_D	Drain Current	$T_c=25^\circ\text{C}$	A
		$T_c=100^\circ\text{C}$	35.4
V_{GSS}	Gate Threshold Voltage	± 25	V
E_{AS}	Single Pulse Avalanche Energy (note1)	490	mJ
I_{AR}	Avalanche Current (note2)	50	A
P_D	Power Dissipation ($T_c=25^\circ\text{C}$)	120	W
T_j	Junction Temperature(MAX)	150	$^\circ\text{C}$
T_{stg}	Storage Temperature	-55~+150	
T_L	Maximum lead temperature for soldering purpose, 1/8" from case for 5 seconds	300	

Thermal Characteristics

Symbol	Parameter	Typ.	MAX.	Unit
$R_{\theta JC}$	Thermal Resistance,Junction to Case	-	1.24	$^\circ\text{C}/\text{W}$
$R_{\theta JA}$	Thermal Resistance,Junction to Ambient	-	62.5	
$R_{\theta CS}$	Thermal Resistance,Case to Sink	-	0.5	

Electrical Characteristics Tc=25°C unless otherwise noted						
Symbol	Parameter	Test Condition	Min.	Typ.	Max	Units
Off Characteristics						
BV _{DSS}	Drain-Source Breakdown Voltage	ID=250 μA, VGS=0	60	--	--	V
△BV _{DSS} / △T _J	Breakdown Voltage Temperature Coefficient	I _D =250 μA, Reference to 25°C	--	0.06	--	V/°C
IDSS	Zero Gate Voltage Drain Current	Vds=60V, Vgs=0V	--	--	1	μA
		Vds=48V, Tc=125 °C			10	μA
IGSSF	Gate-body leakage Current, Forward	Vgs=+25V, Vds=0V	--	--	100	nA
IGSSR	Gate-body leakage Current, Reverse	Vgs=-25V, Vds=0V	--	--	-100	nA
On Characteristics						
V _{GS(th)}	Date Threshold Voltage	Id=250uA, Vds=Vgs	2	--	4	V
R _{DS(on)}	Static Drain-Source On-Resistance	Id=25A, Vgs=10V	--	--	0.022	Ω
Dynamic Characteristics						
C _{iss}	Input Capacitance	VDS=25V, VGS=0, f=1.0MHz	--	1180	1540	pF
C _{oss}	Output Capacitance		--	440	580	pF
C _{rss}	Reverse Transfer Capacitance		--	65	90	pF
Switching Characteristics						
T _{d(on)}	Turn-On Delay Time	VDD=250V, ID=25A RG=25 Ω (Note 3,4)	--	15	40	nS
T _r	Turn-On Rise Time		--	105	220	nS
T _{d(off)}	Turn-Off Delay Time		--	60	130	nS
T _f	Turn-Off Fall Time		--	65	140	nS
Q _g	Total Gate Charge	VDS=400, VGS=10V, ID=25A (Note 3,4)	--	31	41	nC
Q _{gs}	Gate-Source Charge		--	8	--	nC
Q _{gd}	Gate-Drain Charge		--	13	--	nC
Drain-Source Diode Characteristics and Maximum Ratings						
I _S	Maximum Continuous Drain-Source Diode Forward Current	--	--	50	A	
I _{SM}	Maximum Pulsed Drain-Source Diode Forward Current	--	--	200	A	
V _{SD}	Drain-Source Diode Forward Voltage	Id=25A	--	--	1.5	V
t _{rr}	Reverse Recovery Time	I _S =25A, V _{GS} =0V	--	52	--	nS
Q _{rr}	Reverse Recovery Charge	di _F /dt=100A/ μ s (Note 3)	--	75	--	μ C
*Notes 1, L=9.3mH, IAS=50A, VDD=50V, RG=25Ω, Starting TJ =25°C 2, Repetitive Rating : Pulse width limited by maximum junction temperature 3, Pulse Test : Pulse Width ≤ 300μs, Duty Cycle ≤ 2% 4, Essentially Independent of Operating Temperature						

Typical Characteristics

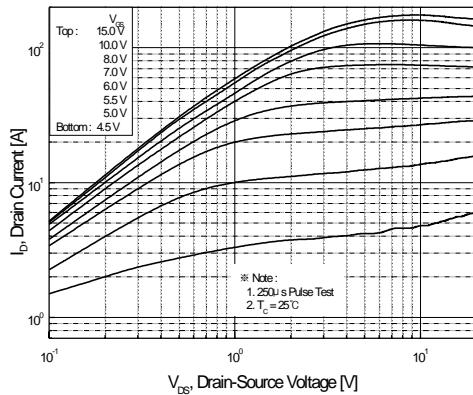


Figure 1. On-Region Characteristics

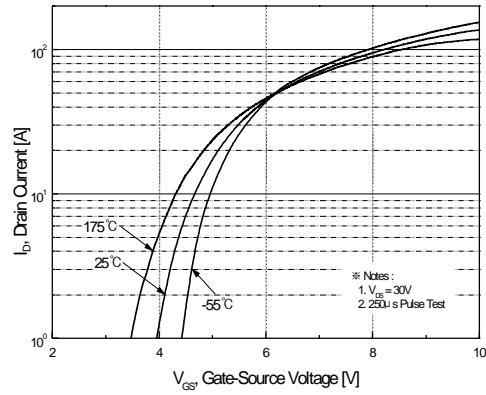


Figure 2. Transfer Characteristics

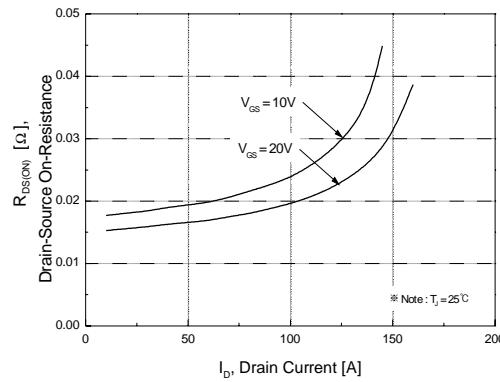


Figure 3. On-Resistance Variation vs. Drain Current and Gate Voltage

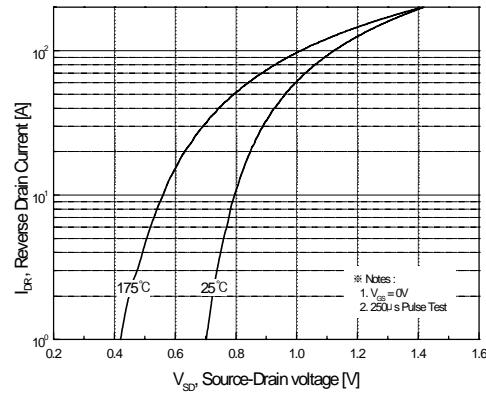


Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperature

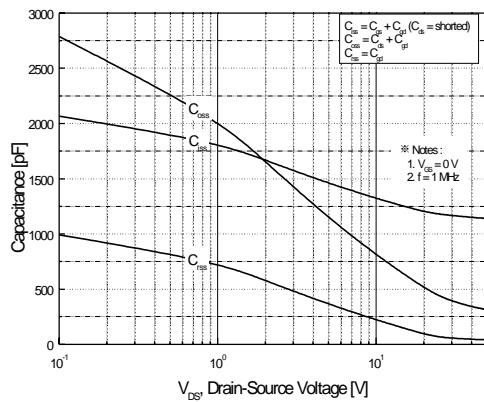


Figure 5. Capacitance Characteristics

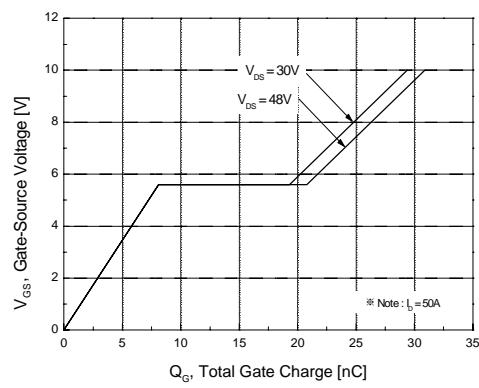


Figure 6. Gate Charge Characteristics

Typical Characteristics (Continued)

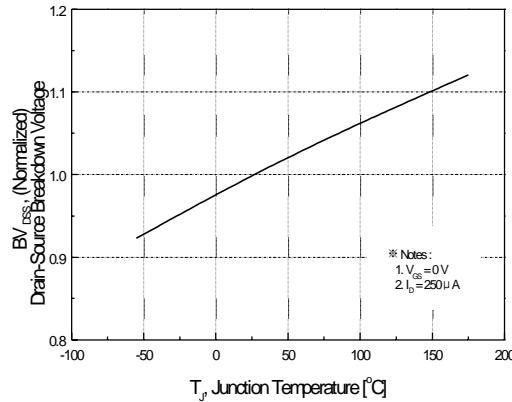


Figure 7. Breakdown Voltage Variation vs. Temperature

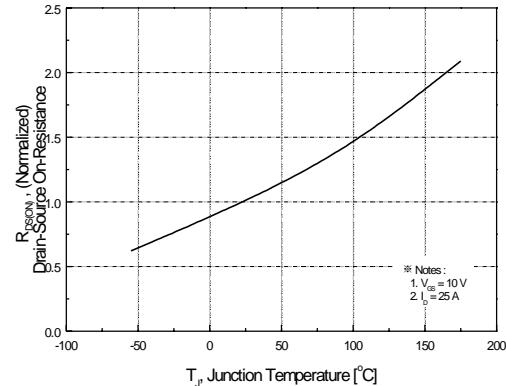


Figure 8. On-Resistance Variation vs. Temperature

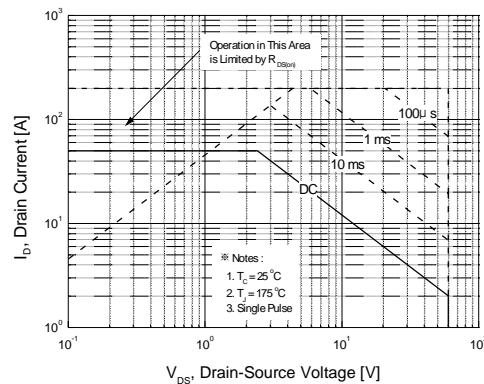


Figure 9. Maximum Safe Operating Area

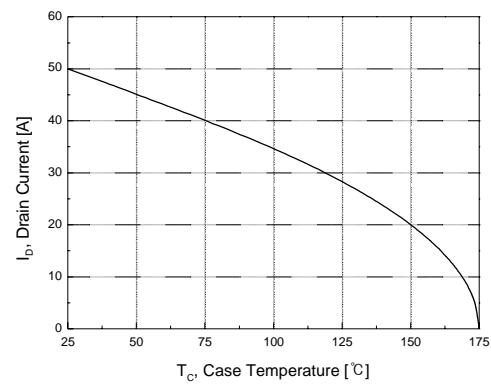


Figure 10. Maximum Drain Current vs. Case Temperature

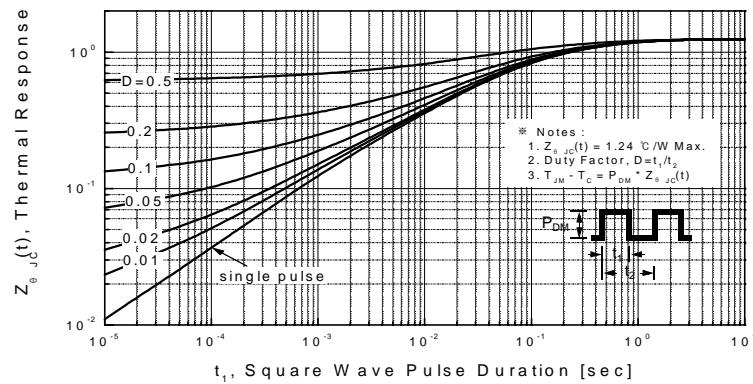
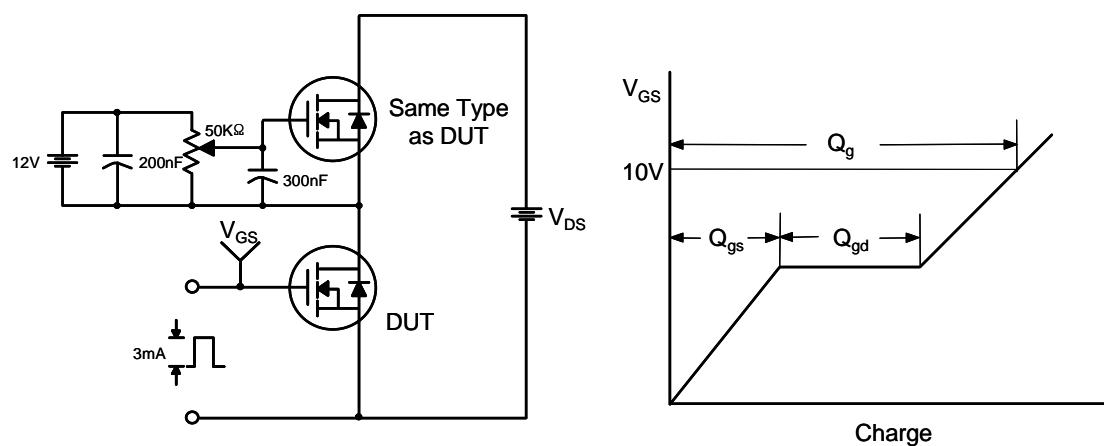


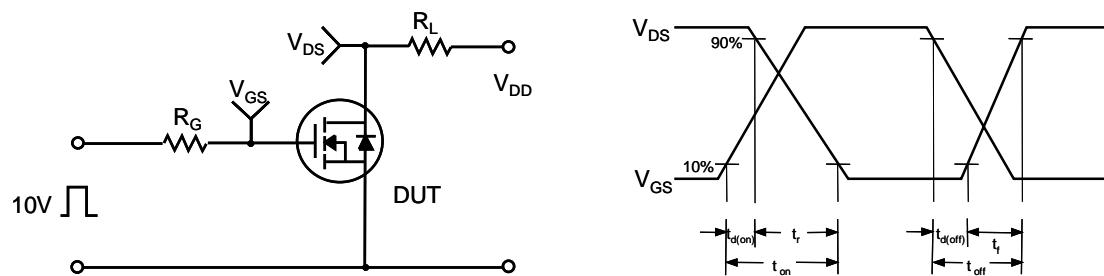
Figure 11. Transient Thermal Response Curve

Typical Characteristics (Continued)

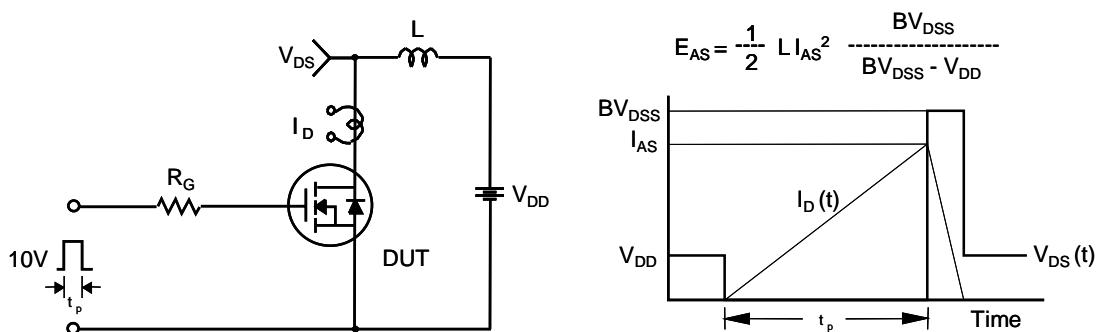
Gate Charge Test Circuit & Waveform



Resistive Switching Test Circuit & Waveforms

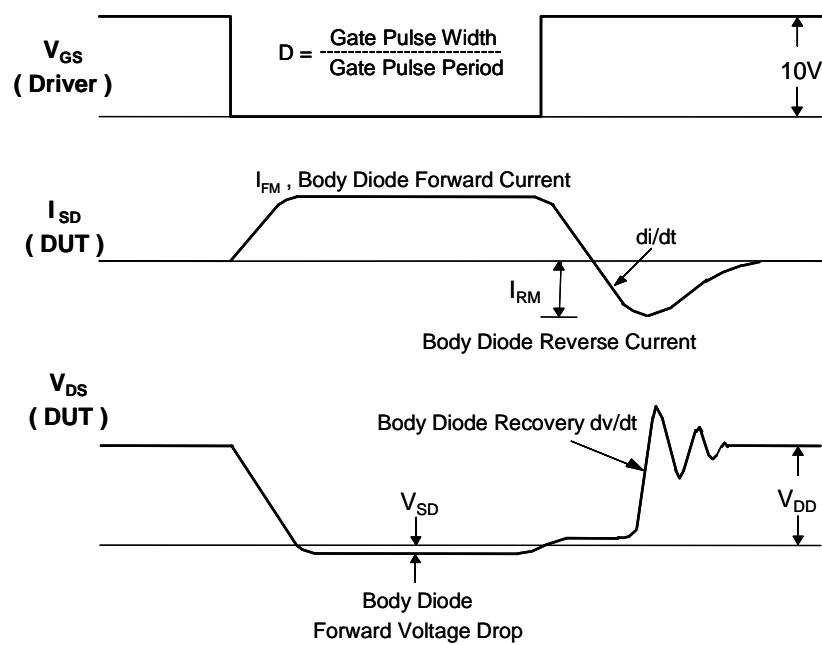
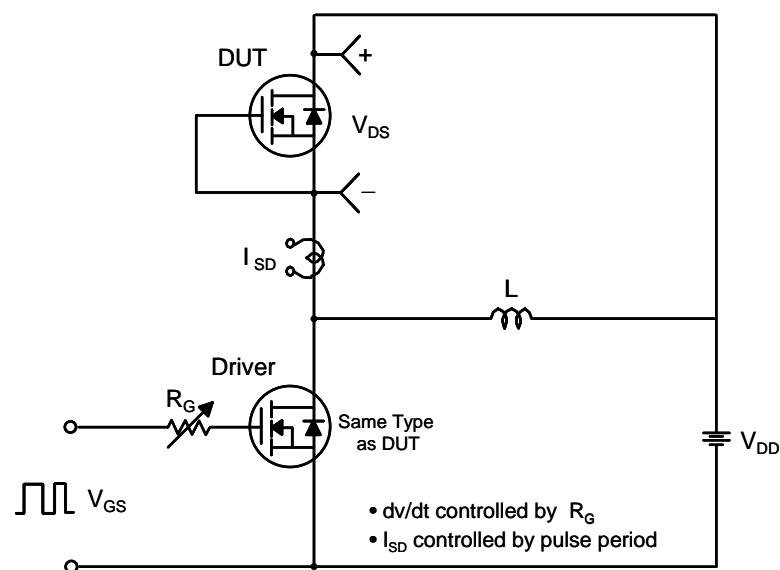


Unclamped Inductive Switching Test Circuit & Waveforms



Typical Characteristics (Continued)

Peak Diode Recovery dv/dt Test Circuit & Waveforms



Package Dimension

TO-220

Unit: mm

